

LINEAR TECHNOLOGY MATERIALS DECLARATION

LT1086CM-3.3#PBF		(Engineering Calculation)		DDPAK				
(printed on: 7/16/2011 12:16:38 PM)				TOTAL MASS (g):		1.374784		
COMPONENT	VENDOR/	CONSTITUENT	CAS	CONSTITUENT	CONSTITUENT	CONSTITUENT		
MATERIAL	INDUSTRY NAMES	NAME	NUMBER	MASS (g)	(PPM) OF MATERIAL	(PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.004012	1000000	2918.277		
Die Coat	Dow Corning	Silicone	67762-90-7	0	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.827657	998500	602027.1		
		Iron (Fe)	7439-89-6	0	0	0		
		Phosphorus (P)	7723-14-0	0	0	0		
		Zinc (Zn)	7440-66-6	0	0	0		
		Nickel (Ni)	7440-02-0	0	0	0		
		Silicon (Si)	7440-21-3	0	0	0		
		Magnesium (Mg)	7439-95-4	0	0	0		
		Tin (Sn)	7440-31-5	0.001243	1500	904.1422		
		Lead Frame Total:				0.830143	1000000	603835.3
Plating	PMI	Exter. Plating Pb	7439-92-1	0	0	0		
		Exter. Plating Sn	7440-31-5	0.009684741	1000000	7044.556		
		External Plating Total:				0.009684741	1000000	7044.556
		Inter. Plating Ni	7440-02-0	0.005	781250	3636.936		
		Inter. Plating Ag	7440-22-4	0.0014	218750	1018.342		
		Internal Plating Total:				0.0064	1000000	4655.277
Die Attach	95Pb / 5 Sn	Silver (Ag)	7440-22-4	0	0	0		
		Tin (Sn)	7440-31-5	9.80E-05	50000	71.28394		
		Lead (Pb)	7439-92-1	0.001853	950000	1347.848		
		Silica (SiO2)	60676-86-0	0	0	0		
		Metal Oxide		0	0	0		
		Antimony (Sb)	7440-36-0	0	0	0		
		Resin (EP)		0	0	0		
Die Attach Total:				0.001951	1000000	1419.132		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.053704	103000	39063.6		
		Bromine (Br)	40039-93-8	0	0	0		
		Silica (SiO2)	60676-86-0	0.466653	895000	339437.4		
		Antimony	1309-64-4	0	0	0		
		Trioxide (Sb2O3)						
		Metal Hydroxid		0	0	0		
		Carbon Black (C)	1333-86-4	0.001043	2000	758.6648		
Encapsulation Total:				0.5214	1000000	379259.6		
Bond Wire	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.001193	1000000	867.7728		
Estimated								
				TOTAL MASS (g):		1.374784		